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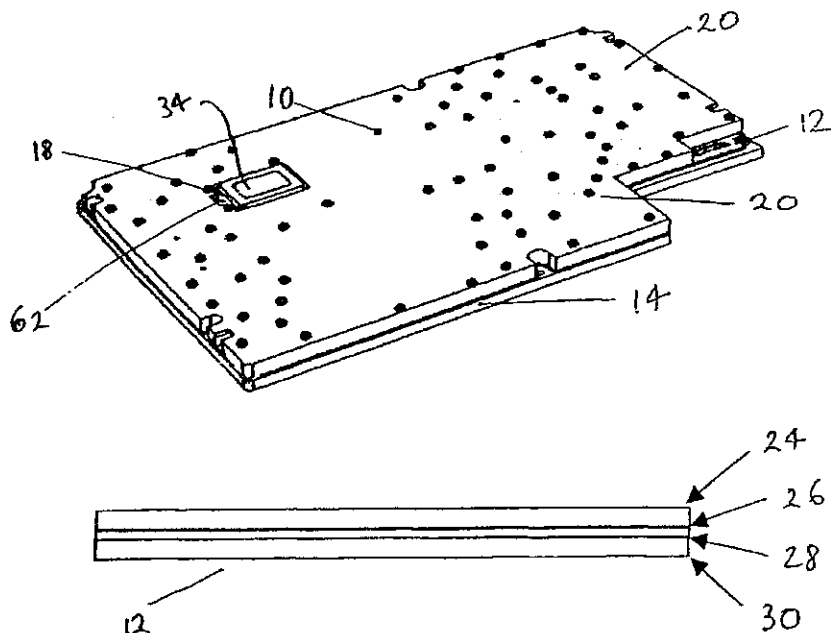
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(54) Title: RADIO FREQUENCY TRANSCEIVERS



(57) Abstract: A radio frequency transceiver having a printed circuit board (PCB) on which are located a plurality of components, the PCB being sandwiched between a base and a cover. The cover having a plurality of components for accommodating each of the plurality of components to separate the plurality of components into a number of virtual modules. All interconnects between the number of virtual modules are in the PCB. The PCB has a radio frequency (RF) layer, a RF ground layer, a direct current (DC) layer, and a DC ground layer. There is a plurality of via holes from the RF ground layer to the DC ground layer to provide virtual RF ground.



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